BAF-717

No Clean Tacky Paste Flux

RoHS compliant

Product Description

BAF717 is a no-clean assembly flux specially designed for ball-attach, BGA re-balling, BGA rework and PoP applications. BAF717 can be transferred to the pad by pin-transfer or ball-dip process involving a rotating disc a doctor's blade for flux levelling or a drum fluxer. The operating-life is >16 hours without much change in viscosity. BAF717 can also be dispensed for BGA or SMD rework. It is recommended for reflow in nitrogen (N_2) with a maximum oxygen (O_2) level of 5000ppm. Post-soldered residue is low and can be left on the circuit. If desired, the residue can be removed with standard cleaners and megasonic energy.

BAF-717 has been optimised to have an unbeatable list of benefits, some are:

- Mild flux chemistry – no-clean flux design.
- Halogen-zero (ROL0) flux system – no corrosion.
- Trouble-free dispensing and dipping – no tailing and no choking till syringe is empty.
- High tack force – secures component in place prior to reflow.
- Fast wetting – smooth solder joint.
- Cosmetically clean appearance – low residue.
- No Head-in-Pillow effect – good electrical conductivity.
- Negligible interfacial void – high joint reliability.
- No-clean formulation – if desired, residue can be removed with standard cleaners with megasonic energy.

Application

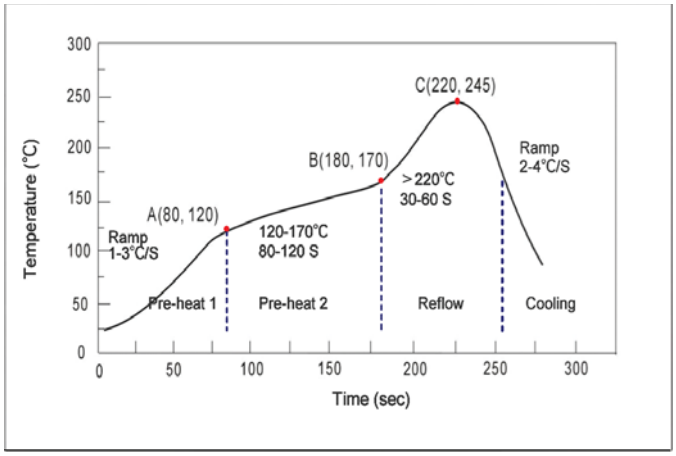
BAF-717 is great for general lead free and leaded applications and also rework applications of various electronic devices. It is ideally suited for applications such as pin transfer, ball dip process and stencil printing process.
For a 0.2 x 0.2mm pad, ca 100µl of flux may be acceptable for good soldering. The chip should be pressed into the flux and make contact with the pad. These are intended for minimal risk of chip movement during reflow. For dipping or pin transfer, flux should cover 50-70% of the ball height.

Specification (*Preliminary*)

Item	Result
Viscosity	35 +/- 5 Pa.s
Density	0.92 g/cm^3
Halide Content JIS Z 3197 8.1.4.2.1	Not added
Copper Mirror Test IPC-TM-650 2.3.32 JIS Z 3197 8.4.2	Classified as "L", Pass
Copper Corrosion Test IPC-TM-650 2.6.15 JIS Z 3197 8.4.1	Pass
Flux Activity Classification IPC J-STD-004	ROL0
Surface Insulation Resistance (85°C, 85%RH, 168hrs) IPC-TM-650 2.6.3.3	> 1 x 10^8 Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs) IPC-TM-650 2.6.14.1	Pass

Recommended Reflow Profile

BAF717 can be used in nitrogen (N_2) to solder SAC alloys with the following profile:



Residue Removal

Post-soldered residues of BAF717 can be removed by most commercial solvent.

Storage, Handling and Shelf Life

Paste flux has to be thawed to room temperature (~25°C) prior using to avoid condensation. Paste flux left on the stencil should not be put back into the container together with the unused paste flux. It is preferable not to re-use paste flux left on the stencil after printing. BAF-717 can be stored at 15-25°C and used within 6 months.

Health and Safety

Do not handle the paste flux with your bare hand. Use proper tool when handling the paste flux. If the paste flux touches the skin, wash thoroughly with soap and water. For more information, please refer to Material Safety Data Sheet.paste touches the skin, wash thoroughly with soap and water. For more information, please refer to Material Safety Data Sheet.

Packaging

BAF-717 paste flux is available in 10gm and 30gm luer-lok syringes. For other packaging requirements, please contact Asahi sales department.

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